#### FORM 6-K

#### SECURITIES AND EXCHANGE COMMISSION

Washington, D.C. 20549

For the month March 2024 No. 3

#### TOWER SEMICONDUCTOR LTD.

(Translation of registrant's name into English)

Ramat Gavriel Industrial Park
P.O. Box 619, Migdal Haemek, Israel 2310502

(Address of principal executive offices)						
Indicate by check mark whether the registrant files or will file annual reports under cover Form 20-F or Form 40-F.						
Form 20-F $\boxtimes$ Form 40-F $\square$						
ndicate by check mark whether the registrant by furnishing the information contained in this Form is also thereby furnishing the information to the Commission pursuant to Rule 12g3-2(b) under the Securities Exchange Act						
Yes □ No ⊠						
1934.	Indicate by check mark whether the registrant files or will file annual reports under cover Form 20-F or Form 40-F.  Form 20-F $\boxtimes$ Form 40-F $\square$ Indicate by check mark whether the registrant by furnishing the information contained in this Form is also thereby furnishing the information to the Commission pursuant to Rule 12g3-2(b) under the Sec					

On March 19, 2024, the Registrant reports TSEM Israeli Capital Market Presentation

March 19, 2024

SIGNATURES

Pursuant to the requirements of the Securities Exchange Act of 1934, the registrant has duly caused this report to be signed on its behalf by the undersigned, thereunto duly authorized.

TOWER SEMICONDUCTOR LTD.

Date: March 19, 2024

By: /s/ Nati Somekh
Name: Nati Somekh
Title: Corporate Secretary



## כנס שוק ההון הישראלי

יום שלישי 19.3.2024

#### Safe Harbor

This presentation contains forward-looking statements within the meaning of the "safe harbor" provisions of the Private Securities Litigation Reform Act of 1995. These statements are based on management's current expectations and beliefs and are subject to a number of risks, uncertainties and assumptions that could cause actual results to differ materially from those described in the forward-looking statements. All statements other than statements of historical fact are statements that could be deemed forward-looking statements. For example, statements regarding expected (i) customer demand, (ii) utilization and cross utilization of our Fabs, (iii) demand from our end markets, (iv) market and technology trends, and (v) results regarding revenues, cash flow, margins and net profits are all forward-looking statements. Actual results may differ materially from those projected or implied by such forward-looking statements due to various risks and uncertainties applicable to Tower Semiconductor's business as described in the reports filed by Tower Semiconductor Ltd. ("Tower") with the Securities and Exchange Commission (the "SEC") and the Israel Securities Authority ("ISA"), including the risks identified under the heading "Risk Factors" in Tower's most recent filings on Forms 20-F and 6-K. No assurances can be given that any of the events anticipated by the forward-looking statements will transpire or occur, or if any of them do, what impact they will have on the results of operations or financial condition of Tower Semiconductor. In addition, some of the financial information in this presentation, is non-GAAP financial measures, including, but not limited to, EBITDA, Cash, debt and Net Cash. These non-GAAP financial measures have the same definition as appear in our previously filed quarterly financial results related announcements and/ or other public filings.

Tower Semiconductor is providing this information as of the date of this presentation and expressly disclaims any obligation to update any of the forward-looking statements or other information contained in this presentation as a result of new information, future events or otherwise.





יום שלישי 19.3.2024

## **Agenda**

**CEO Keynote** 

Russell Ellwanger, CEO

**Technology Leadership & Served Markets** 

Dr. Avi Strum, CTO

**Operational Excellence** 

Rafi Mor, COO

**Financial Strength** 

Oren Shirazi, CFO

**Q&A Panel** 

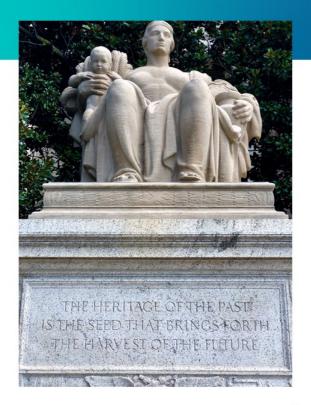
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# Partnership, Leadership, Impact, Innovation Excellence

Russell Ellwanger, CEO



Washington, D.C. Statue on the left of the main entrance to the National Archives of the United States bears the inscription:

## "The heritage of the past is the seed that brings forth the harvest of the future"

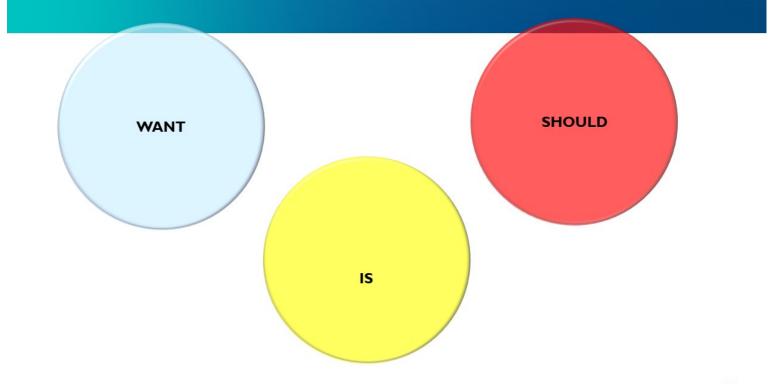






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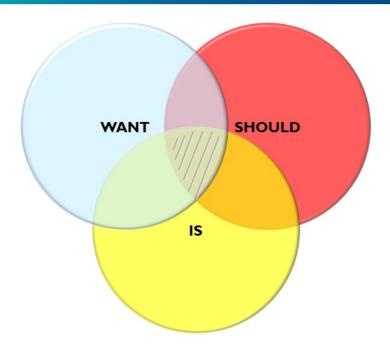




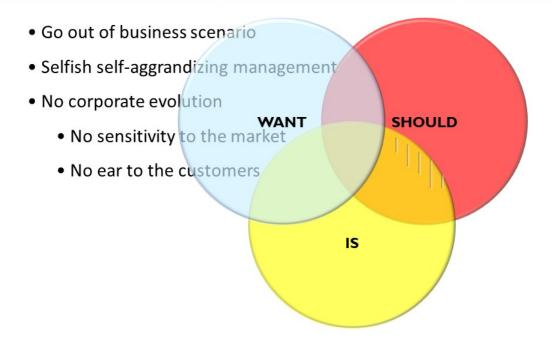
#### **Our Vision:**

Provide the highest value analog semiconductor solutions as validated by our customers, employees, shareholders and partners.

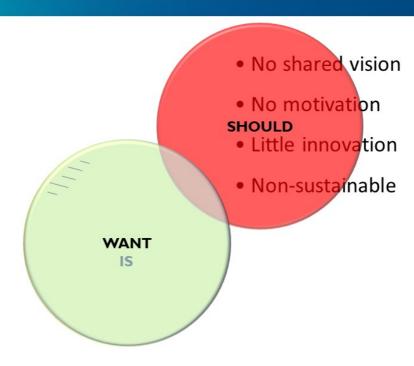




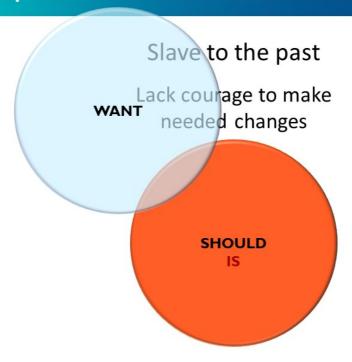




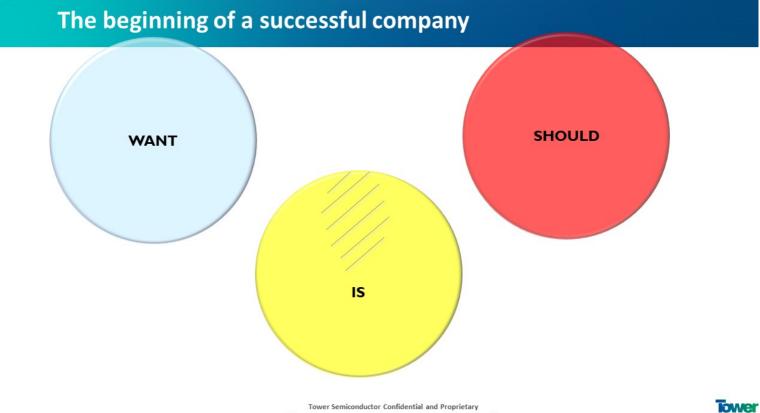






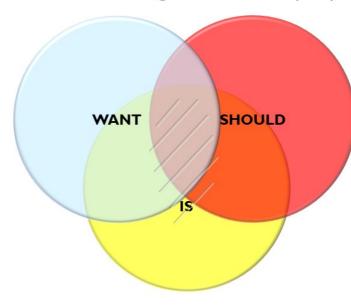








#### Can increase degree of overlap by being:

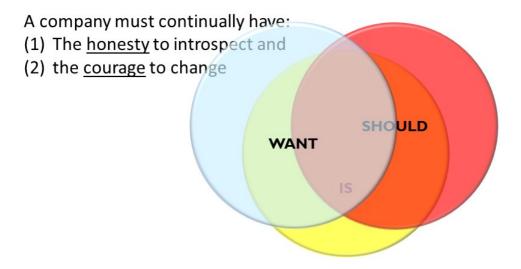


- Customers centric
- Setting and evaluating realistic but stretch-goals with definitive metrics
- Requires continual rapid cycles of learning





Even once aligned, market/customers insensitivity can cause them to move apart.







#### **Value Vectors**

Being a trusted long-term

employees and shareholders

partner for customers,

We pursue excellence in all we do from ideation through product shipment. Hence, we deliver the best experience to our customers and employees

Excellence
Effective, Efficient,
Highest Quality
Embedded in everything
that we do

Leading the analog ecosystem with technology and process solutions in exciting and growing markets



## Tower Semiconductor and InnoLight Partner to Develop Multi-Generation Silicon Photonics Based Optical Transceivers

400G/800G Transceivers built on Tower's production PH18M Silicon Photonics platform

Partnership to deliver solutions for the growing markets of Artificial Intelligence (AI), Datacenter Interconnects and Next-Gen Telecom

MIGDAL HAEMEK, Israel, and SUZHOU, China, Sept. 7, 2023 – Tower Semiconductor (NASDAQ/TASE: TSEM), a leader in high-value analog semiconductor foundry solutions, and InnoLight Technology, the leader in data center optics, today announced their collaboration to develop multi-generation high-speed optical transceivers based on Tower's Silicon Photonics process platform (PH18). With production already underway, this strategic partnership is expected to enable cutting-edge solutions to support the growing demands of Al, datacenters, and next-generation telecom networks. According to Yole, a market research firm, the silicon photonic die market is expected to grow at 22% CAGR reaching nearly half-a-billion dollars by 2027.

#### Coherent Awards Tower Semiconductor as an Outstanding Innovation and Technology Supplier for Silicon Photonics based Products

Tower's silicon photonics technology to be deployed by Coherent across multiple data rates for high-speed optical transceivers needs Technology for Micro Displays

PITTSBURGH, PA, and MIGDAL HAEMEK, Israel, March 18, 2024—Coherent Corp. (NYSE: COHR), a global leader in materials, networking, and lasers, and Tower Semiconductor (NASDAQ/TASE: TSEM), the leading foundry of high-value analog semiconductor solutions, today announced that Coherent has recognized Tower Semiconductor as an Outstanding Innovation and Technology Supplier for its silicon photonics based optical transceiver products. This prestigious award recognizes Tower's unwavering long-term commitment to providing the most advanced technology solutions, enabling the development of Coherent's market-leading multiple data rate nodes for high-speed optical transceivers based on Tower's PH18 silicon photonics process technology. According to the Yole Group, the silicon photonics market is expected to grow at 44% CAGR from 2022 to 2028, supporting growth of AI, Data Center, and Network infrastructure.

Tower Semboridation

Ranking of Top 10 Transceiver Suppliers						
2010	2016		2018	2022		
Finisar	Finisar	1	Finisar	Innolight & Coherent		
Opnext	Hisense	2	Innolight	(tie)		
Sumitomo	Accelink	3	Hisense	Cisco (Acacia)		
Avago	Acacia	4	Accelink	Huawei (HiSilicon)		
Source Photonics	FOIT (Avago)	5	FOIT (Avago)	Accelink		
Fujitsu	Oclaro	6	Lumentum/Oclaro	Hisense		
JDSU	Innolight	7	Acacia	Eoptolink		
Emcore	Sumitomo	8	Intel	HGG		
WTD	Lumentum	9	AOi	Intel		
NeoPhotonics	Source Photonics	10	Sumitomo	Source Photonics		

6 of the top 10 are our active customers (not Huawei). Source: LightCounting

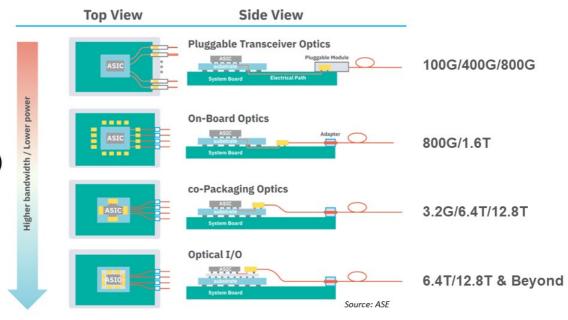
To note: Coherent is a result of an acquisition of Finisar.



#### Silicon Photonics: From Pluggable to CPO to Optical I/O

## Silicon Photonics enables

- Higher Bandwidth (Gbps)
- Lower Power (pJ/bit)
- Lower Cost (\$/Gbps)









#### **Financial Metrics of Excellence**

- Effective ~ Gross Margin
  - High value offerings that enable customers at high capacity scale.
- Efficient ~ Point drop from Gross Margin to Operating Margin
  - · Tower is a benchmark at about 10 points
  - Streamlined infrastructure leads to fast decision making and fast execution
    - Tower's process flow development is done in the Fab that will be running the flow => speed to ramp.
    - · All process engineers are R&D engineers!

**Tower** 

#### Financial Metrics of Excellence (cont.)

#### • Highest Quality

• Tower top 20% by ranking and rating has a benchmark low attrition rate

	Actual		Actual
2023	2.4%	2015	2.2%
2022	3.0%	2014	3.8%
2021	3.4%	2013	3.4%
2020	1.5%	2012	4.4%
2019	2.4%	2011	2.6%
2018	0.9%	2010	2.2%
2017	3.7%	2009	2.3%
2016	0.5%		

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## Alice in Wonderland | Lewis Carroll Alice approaching a crossroad, asked the Cheshire Cat

**Alice**: "can you please tell me which way I ought to go from here?"

Cat: "that depends a good deal on where you want to get

Alice: "I don't much care where"

Cat: "then it doesn't much matter which way you go..."



# We know where we are going!

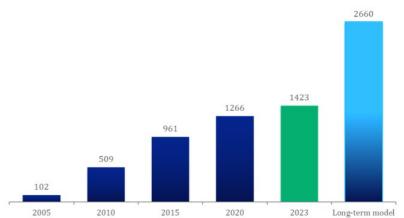




#### "What is past is prologue"



We have a rich past, an introduction for each of us to write the most amazing new chapter in the book of Tower.







## **Technology Leadership and Served Markets**

Dr. Avi Strum, CTO

#### Tower Semiconductor (NASDAQ/TASE: TSEM)

#### **Analog Pure play foundry**

• Serving over 300 customers globally

#### Analog technology leadership

· Focus on RF, Power, Sensors & Displays

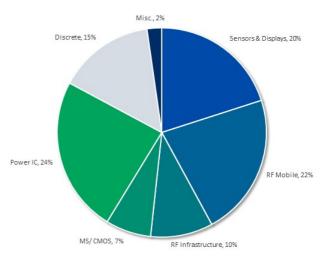
#### Serving a wide range of end-markets

 Infrastructure, automotive, mobile, medical, industrial, consumer, aerospace and defense

#### **Operational Excellence**

Multi-fab production options across three geographic regions

#### 2023 Revenue Breakdown





### **RF Infrastructure**

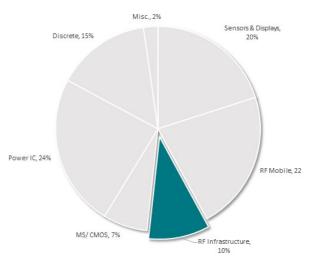
#### Datacom, Telecom and Artificial Intelligence





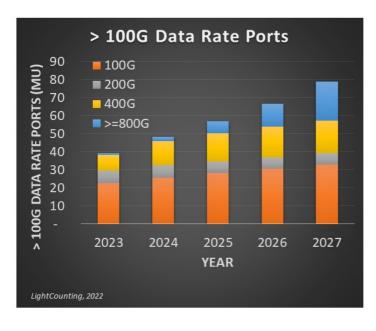
Optical Fiber Transceivers

HP SiGe and Si Photonics





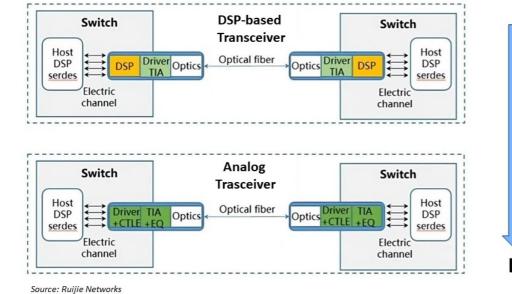
#### **Growth of Optical Transceivers**



- Historically our market has been exclusively of SiGe optical transceiver components (drivers, TIAs, CDRs)
- Today, we are adding Silicon Photonics components at higher data-rates (400/800 G)
- Working with >50 active Silicon Photonics customers, announced production and partnerships with Innolight and Coherent (#1, #2 optical module providers) and Marvell (Tier 1 optical transceiver IC provider)



## Silicon Germanium: Linear Pluggable Optics (LPO) boosting SiGe opportunity



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Linear Drive (no DSP)

**Lower Cost** 

**Lower Power** 

**Lower Latency** 

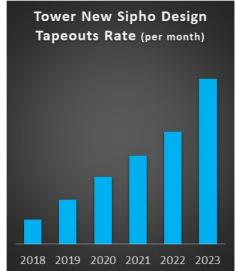
Larger market for SiGe

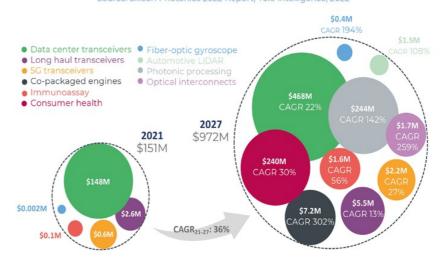


#### **Silicon Photonics Market**

#### 2021-2027 SILICON PHOTONIC DIE FORECAST BY APPLICATION

Source: Silicon Photonics 2022 Report, Yole Intelligence, 2022





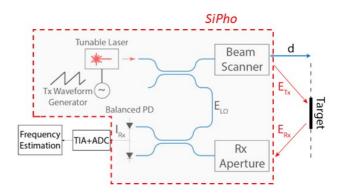
YOLE Intelligence

www.yolegroup.com | ©Yole Intelligence 2022



#### SiPho based FMCW benefit for LiDAR

- FMCW LiDAR gives both the range (x, y, and z coordinates) and the relative velocity of surrounding objects, making it best suited for automotive applications
- SiPho enables a compact integration of all optical elements of an FMCW LiDAR: laser sources, optical modulators, mux/demux, couplers and photodetectors etc.
- SiPho also enables on-chip integration of Optical Phase Arrays (OPAs) for scanning the beam with high speed and reliability (no moving parts).



Adapted from Rezaei et al, Univ. of Washington (ASHES '22)





#### Satellite based internet services

- · Terrestrial receiver demand is growing
- SiGe based phased-array are key enablers
- ~250 phase-array ICs per terminal on average
- 80M\* new users expected over the next decade can drive an additional ~\$400M/year SiGe market

Collaboration with Renesas to Manufacture SiGebased Beamforming ICs for Tier-1 Customers in Satcom, 5G, and Aerospace & Defense Applications







<sup>\*</sup> Euroconsult



#### Tower Semiconductor Collaborates with Renesas to Manufacture SiGe-based Beamforming ICs for Tier-1 Customers in Satcom, 5G, and Aerospace & **Defense Applications**

The Satcom terrestrial market is expected to grow to 150M users by 2031 according to Euroconsult with the expansion of global satellite-based internet services

MIGDAL HAEMEK, Israel, January 16, 2024 - Tower Semiconductor (NASDAQ/TASE: TSEM), the leader in high-value analog semiconductor foundry solutions, today announced a collaboration with Renesas, leveraging Tower's high-volume and high-performance SiGe BICMOS technology to manufacture SiGe-based beamforming ICs. This strategic collaboration underscores Renesas' commitment to innovation as its broad portfolio of beamforming products has already achieved design wins by key worldwide players across 5G, satcom and Aerospace & Defense markets, positioning the company at the forefront of the industry.

The Satcom terrestrial terminal market is growing rapidly as satellite-based internet services proliferate globally. According to Euroconsult, a market research firm, 71 million people were connected to satellite broadband services in 2022. With rapid deployment of LEO satellite constellations, this number is expected to double in 2031, reaching over 150 million users. This translates to an increase of \$400M in the average yearly TAM for SiGe wafers over the coming decade.

"The unique advantages of Tower's SiGe BiCMOS technology have empowered us to design and manufacture highly integrated and power efficient semiconductors that set new industry benchmarks," said Naveen Yanduru, VP of RF Communications at Renesas. "As evidenced by our design wins and volume shipments, the displacement of mechanical antennas by highly agile electronically steered antennas (ESAs) is well underway and will continue to drive exponential SAM growth for beamforming ICs in the coming years. With the continuously surging demand for millimeter-wave technology, our collaboration with Tower Semiconductor has positioned Renesas as a market leader," Mr. Yanduru added.

Renesas is a global leader in delivering cutting-edge solutions for the telecommunications industry and has made strides in the Satcom and 5G  $markets through its collaboration with Tower Semiconductor. \ This capability played a significant role in empowering Renesas to establish and the semiconductor of the semicon$ solidify its market leadership.

"We are excited to partner with Renesas in bringing these breakthrough products to market leveraging our industry leadership in SiGe foundry technology along with their strong product development, talent and market presence," noted Dr. Marco Racanelli, President at Tower

"Our global capacity and engineering agility will ensure Renesas has both the ability to develop new, high-performance products and deliver these in high-volume to their Tier 1 customers."

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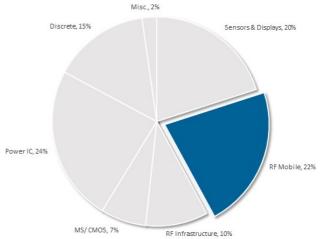
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## **RF Mobile**

Wireless Front-End Components Built on RF SOI and RF SiGe

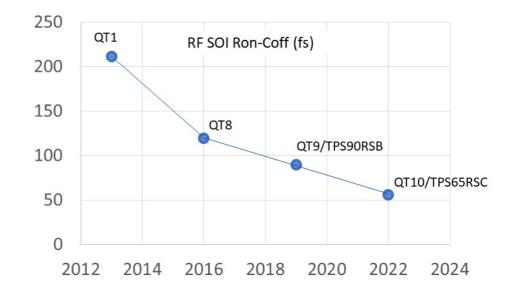






## RF SOI figure of merit roadmap

- 200mm and 300mm wafer sizes
- 180nm to 65nm nodes
- 4 factories in high volume + qualifying Agrate, Italy
- Best-in-class FoM and roadmap with low Ron-Coff and high power handling





## **RF Mobile Market**

# Wireless Front-End Built on RF SOI and RF SiGe Platforms

RF Switch RF SOI

Antenna Tuner RF SOI

Low-noise Amplifier SiGe / RF SOI

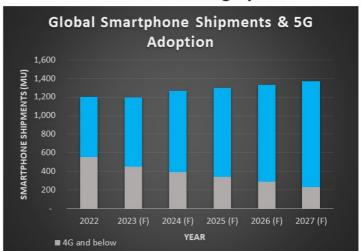
Power Amplifiers SiGe / RF SOI

mmWave SiGe / RF SOI





# 5G adoption drives steady growth in RF content with 6G coming by 2030





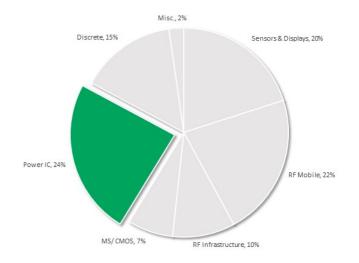
# **Power and Mixed-Signal**

#### **Largest Analog Market**

• \$24B 2024 Power IC market per Yole

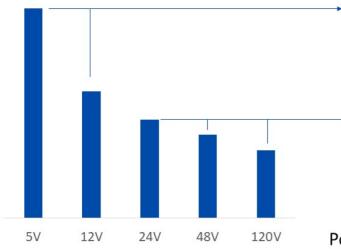
### Serving all major Semi Segments

- Automotive
- Industrial
- Consumer
- Infrastructure





## Power IC Market (~\$24B\* Total)



#### 8

Market Size vs. Operating Voltage

\* Yole: 2024 Power IC market

#### **Newer 300mm Markets for Tower**

- 65nm BCD with best-in-class Rdson/efficiency
- · Mobile, battery operated applications

#### **Traditional 200mm Markets for Tower**

- · 180nm BCD with rich analog features
- Automotive, Industrial, and Infrastructure applications

Poised for strong market share gains in this large market with announced 300mm capacity, 65nm technology, and customers



## **TPS65PM Modularity**

Tower's 65nm BCD technology is based on a modular process that potentially has more than 1000 BEOL 2~6 Cu different flavors Top 0.9 or 3.3um It covers a wide range of Power & Analog applications with best-in-class FOMs 1.2V Core Trans. (MOS, stdcell, SRAM, ePF) This technology has a low mask count, achieved by sharing masks across Analog adders (Hipo, MiM, MoM, Zener) different devices 5V or 3.3V Mixed Signal (MOS/Cap/Diode/BJT/Resistor, poly Fuse, eNVM, ..) Tower Semiconductor Confidential and Proprietary

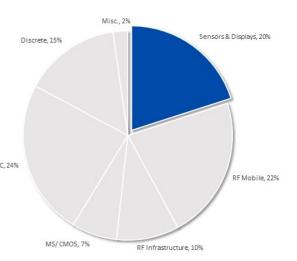
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# Sensors and Displays

#### CMOS Image Sensors High-Value Markets

- Medical
- Industrial
- Automotive





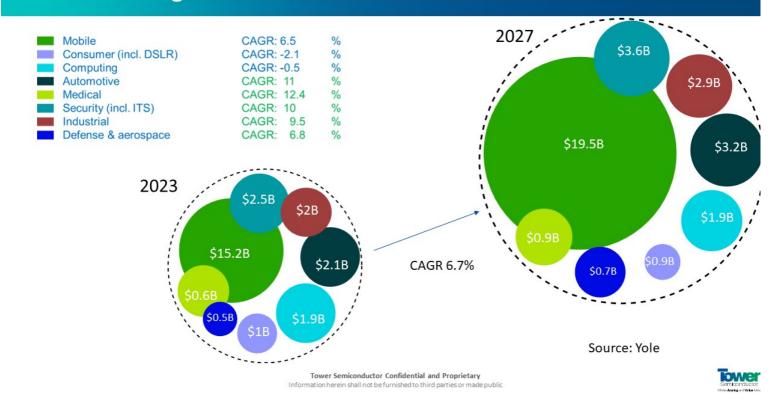


# uLED Display Solutions Emerging, Growth Markets

- AR/VR
- High Resolution Displays



## **CMOS Image Sensor market overview**



## **High Value CIS Markets**





**High value wafers** due to unique stitching technology for large sensors

- · Intra and Extra Oral
- Mammography
- Surgical
- Up to 21cm x 21cm (1 DPW)





#### High-end Photography

**High value wafers** due to unique pixel IP, stitch field for full-frame sensors and stacked BSI technology

- Cinematography
- Broadcasting
- · High end photography





#### **Industrial Machine Vision**

**High value wafers** due to unique global shutter, stitch field and stacked BSI

- 2-D barcode readers
- Food inspection
- Industrial robots
- Display / solar cell inspection
- ITS





## **Emerging High Growth Sensor and Display Markets**



Biometrics Driven mainly by the mobile market

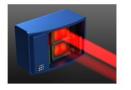
- Optical fingerprint lens-type sensors
- Face recognition (iToF)
- Palm recognition





3D sensing
Driven by high growing
markets such as automotive
(LiDARs) and AR (3D mapping

- Automotive (dToF)
- Gaming (iToF/dToF)
- AR/VR depth sensors
- (LiDARs) and AR (3D mapping) Robotics / Home Robotics (dToF)
  - Fast camera autofocus

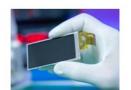




Displays Very high growth market (VR Displays)



- uOLED displays for VR goggles
- uLED on Silicon for next generation displays





# Stitching technology Large Scale image sensor process using stitching 2 masks solutions: Single mask solution Single mask solution Wask A Mask B Printen silicon - no size limitation ABG6 ABG7 ABG8 Single mask solution Full 8" wafer asc Full 8 wafer asc Full 8 wafer asc



## **Tower Operational Strategy**

- ❖ Leverage Tower Global operations to pursue excellence in all what we do.
- Quality, efficiency and effectiveness are the pillars of excellence and are indispensable to each other. We continually drive:
  - · Highest standards of quality
  - Efficiency in processes, systems and procedures
  - Effectiveness in creation and implementation
- ❖ We are Committed to continuous improvement.
  - We continually develop and maintain large wafer capacity with duplication of major process flows across different geographic locations for BCP purposes.
  - ❖ Load the Fabs to high utilization while delivering the best-in-class KPI's.

Semiporducion

## Adding significant 300mm capacity to grow scale

- Six factories in high-volume production
- Two additional 300mm factories being qualified to meet forecasted growing demand with biz models minimizing time to volume and cost.





## **Tower Operations - Global capacity assurance**

- **3.1M Wafers / Year (200mm equivalent).** Enabling 200mm and 300mm multi-fab wafer production.
  - Cross Qualification answer customers BCP needs and maximized utilization and customer assurance
  - · Fab-10 started production ramp in Q1 2024.
  - Fab11 will start production ramp in Q1 2025.









## Operational Excellence – Best in class KPI's among Analog Fabs

Capacity & Utilization

High Asset utilization of ≥85%, with minimal affect on fab performance

Duplicate major flows between Fabs to increase operational flexibility.

2 OSD & Cycle Time

..........

Strive for Best in benchmark OSD and Cycle time

OSD >97% and Cycle time <2.0 DPL at 65nm Technology.

3 Cost Savings Must produce parts at the lowest possible cost

OEE improvement on Bottleneck Tools, Qualify alternative materials and Parts, Reduce material usage, Lower price on same materials.

Quality:
Plant Yield
Die Yield & RMA

Cpk> 1.67,Plant Yield >98%, RMA <0.2%,typical Die Yield >95%.

Support Automotive customers. ISO Certified for : Quality ; Environmental; IP Security; Safety; and Automotive. Reduce CONQ.

New Technologies
Ramp to Mass
Production

Align the Technological Roadmap with customers wants and needs

Transfer new technologies from the R&D to the Fabs and Ramp into mass production with the Quality mentioned above.



## **Operational Excellence - Improve Operational Efficiency**

#### **Global Contracts** Leverage

Company Size



With Power & Bulk Gases suppliers.

**Long Term Contracts** 



#### **Centralized Capex**

Package deals with OEM and 2<sup>nd</sup> source vendors.





#### Reengineering

Eliminate process & Metrology steps Assign to the fastest capable tools.



## Repair & Recycle

Test wafers, Water, H2SO4, etc. Local Repair Lab



#### **Effective** Supply Chain

Lean-**Eliminate** Waste

#### Leverage Global Presence

Increase Assets Utilization

#### **Shared Best Practices**

Global Teamsshare Best Practices and Cross-Fab FMEA



#### **Shared Equipment**

Move Tools from site to site. Sale non utilized tools.



#### **Reduce Scrap and Waste**

Reduce Material consumption

#### **Automation-Dashboard**

Improve Visibility & Standardization



#### **Automation-Scheduler**

Optimize wip management increase Fab Throughput



#### **OEE Improvement**

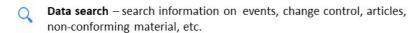
Tool Availability. Redundancy Process throughput

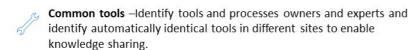




# Global Knowledge platform Sharing

Enabling operation to improve the quality and efficiency by learning proactively from other sites and solved problems faster by consulting organization experts





**Technology search** –Identify technologies experts and identify automatically identical technologies in different sites to enable knowledge sharing.

Tower dictionary – explain Tower terms and abbreviations

**OEE** – global data base of tools performance to state differences between FABs and drive performance to the best one.





## Develop E-learnings, WEB based trainings to improve the skills of all employees in the global operations

Trainings were developed for the following topics: Knowledge sharing, CCB, non-conforming material, Measurement system analysis, Crash, Overall Equipment Effectiveness (OEE), Basic statistics, statistical Hypothesis tests, Statistical Process Control (SPC).



Change Management (CCB)



Non Conforming Material



Measurement System Analysis Operation Under Crash Situation



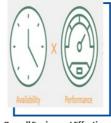


Knowledge Sharing



Basic Statistics





Overall Equipment Effectiveness







## Tower Semiconductor is Going Green, Results also in increase Efficiency

TSEM broadening its presence into renewable energy and green initiatives. **Invested in key projects which enables improvement in water and electricity usage**.



Reduction in power usage by installing solar panels in Fab1&Fab2 Roof with estimated 4400MWh yearly production .



Waste Reduction: Recycle **3K ton/year** of H2SO4



Global initiatives to reduce <u>Electricity consumption</u> of **18,000 MWh/year** such as installing *smart devices* that regulate power consumption, upgrading the chillers, replacing the cooling tower and replacing neon light bulbs with LED bulbs



Total of **774,500 m3/year**water consumption were reduced through recycling projects.

• The total electricity savings per year is equivalent to yearly electricity consumption of about **1800 private households** or 16 million pounds of coal burned



 The total water saving is equal to the annual water consumption of a town with a population of 20000 people

## The Best Confidence Builder is High Yielding Wafer Shipped on Time

#### • Large Capacity Globally and High Assets Utilization:

Quality technologies at multiple TowerJazz Sites to utilize all Fabs at >85%, allowing us to better serve increasing customer demand.

#### Reduced Lead Time:

To shorten Time to Market for new products

→ Fuel our customer's future growth!

#### • Improved Efficiency:

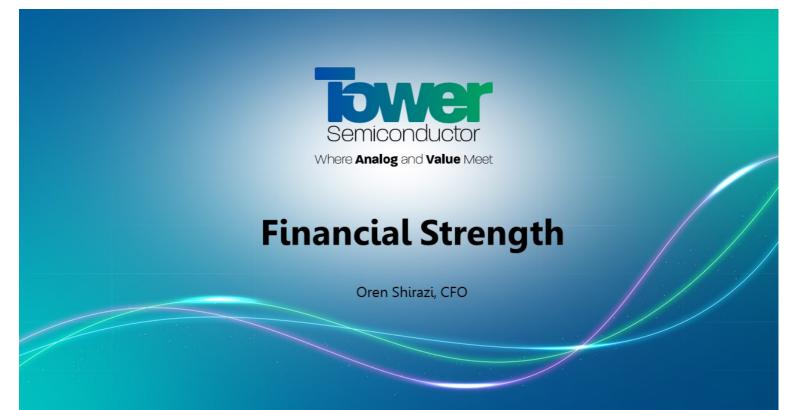
OEE Improvement to reduce Capex investment. COGS Savings maintain competitive

#### • Exceptional Quality:

PPB level Field Failures & High Yields - to delight existing customers and win new







## Financial Model (\$M)

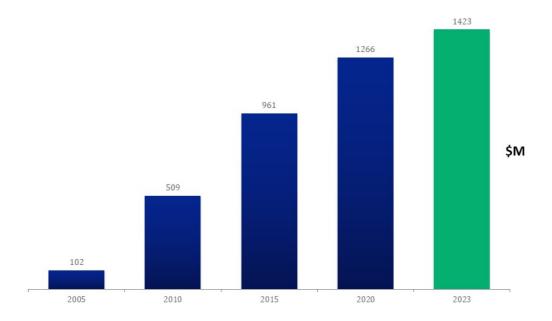


<sup>\*</sup> Including New Mexico capacity corridor and Agrate capacity based on previously announced Cap-Ex investments



 $<sup>{\</sup>it ** Excluding Intel merger contract termination fees received in Q3'2023, net of associated cost and taxes}$ 

# Annual Revenue (5-year Tracking & 2023)





## Balance Sheets (\$ in million)

	December 31, 2023	September 30, 2023	December 31, 2022
CURRENTASSETS			
Cash and cash equivalents	261	315	341
Short-term deposits	791	735	495
Marketable securities	185	179	170
Trade accounts receivable	154	150	153
Inventories	282	304	302
Other current assets	36	34	34
Total Current Assets	1,709	1,717	1,495
Property and equipment, net	1,156	1,062	962
Intangible assets, net	12	13	14
Deferred tax and other long-term assets, net	41	44	77
TOTAL ASSETS	2,918	2,836	2,548
CURRENT LIABILITIES			
Short-term debt	59	48	62
Trade accounts payable	138	106	151
Customer prepayment and deferred revenue	18	24	39
Other current liabilities	61	80	135
Total Current Liabilities	276	258	387
Long-term debt	173	180	210
Customer prepayment	26	30	41
Deferred tax and other long-term liabilities	16	19	21
TOTAL LIABILITIES	491	487	659
Shareholders' Equity	2,427	2,349	1,889
TOTAL LIABILITIES & EQUITY	2,918	2,836	2,548



## Cash Reports (\$ in million)

	Q4'23	Q3′23	Q4'22
Cash opening balance, excluding securities & deposits	315	318	390
Cash from operating activities	126	402*	133
Cap-Ex, net	(136)	(101)	(38)
Investments in securities, deposits & long-term assets	(37)	(318)	(150)
Debt repaid and others, net	(7)	14	6
Cash closing balance, excluding securities & deposits	261	315	341

	FY'23	FY'22
Cash opening balance, excluding securities & deposits	341	211
Cash from operating activities	677 *	530
Cap-Ex, net	(432)	(214)
Investments in securities, deposits & long-term assets	(289)	(116)
Debt repaid and others, net	(36)	(70)
Cash closing balance, excluding securities & deposits	261	341

 $<sup>^{\</sup>star}$  Cash from operations includes Intel termination fee, net of cost, in the amounts of \$314M received in Q3'23 and FY23



# FY'23 P&L vs. FY'22 P&L (in thousands of \$)

		Year ended		
		Dec em	31,	
		2023		2022
REVENUE S	S	1,422,680 \$	3	1,677,614
COST OF REVENUES	_	1,069,161		1,211,306
GROSS PROFIT		353,519		466,308
OPERATING COSTS AND EXPENSES:				
Research and development		79,808		83,911
Marketing, general and administrative		72,454		80,282
Restructuring income, net		(32,506)		(9,559)
Merger-contract termination fee, net		(313,501)	_	
		(193,745)		154,634
OPERATING PROFIT		547,264		311,674
FINANCING AND OTHER INCOME (EXPENSE), NET		37,578		(19,701)
PROFIT BEFORE INCOME TAX		584,842	6/1/2	291,973
INCOME TAX EXPENSE, NET		(65,312)		(25,502)
NET PROFIT		519,530		266,471
NON CONTROLLING INTEREST		(1,036)		(1,902)
NET PROFIT ATTRIBUTABLE TO THE COMPANY	\$	518,494 S		264,569
BASIC EARNINGS PER SHARE	s	4.70 S	3	2.42
DILUTE D E ARNINGS PE R SHARE	S	4.66 S	_	2.39
GAAP NET PROFIT	s	518,494 \$	3	264,569
Stock based compensation		27,931		24,215
Amortization of acquired intangible assets		1,923		2,033
Restructuring income, net		(11,224)		(7,056)
Merger-contract termination fee, net		(289,988)		_
ADJUSTE D NE T PR OFIT	S	247,136 \$		283,761
ADJUSTED DILUTED EARNINGS PER SHARE				
Basic	S	2.24 \$	3	2.60
Diluted	s	2.22 S	<u> </u>	2.56



# Q4'23 P&L vs. Q3'23 and Q4'22 P&L (in thousands of \$)

	Three months ended					d
	December 31,		September 30,		December 31,	
	-	2023		2023	_	2022
REVE NUES	S	351,711	s	358,167	S	403,227
COST OF REVENUES	39	267,294		271,299	-	278,501
GROSS PROFIT OPERATING COSTS AND EXPENSES:		84,417		86,868		124,726
Research and development		20.849		20.176		20,706
Marketing, general and administrative		18,401		18,037		18,880
Restructuring income, net		-				(13,592)
Merger-contract termination fee, net		-		(313,501)		(20,002)
•		39,250		(275,288)		25,994
OPE RATING PROFIT		45,167		362,156		98,732
FINANCING AND OTHER INCOME (EXPENSE), NET		16,682		9,975		(55)
PROFIT BEFORE INCOME TAX		61,849		372,131		98,677
INCOME TAX EXPENSE, NET		(10,130)		(34,394)		(12,835)
NET PROFIT	525	51,719	100	337,737	100	85,842
NON CONTROLLING INTEREST		2,128		4,318		(2,518)
NET PROFIT ATTRIBUTABLE TO THE COMPANY	\$	53,847	\$	342,055	\$	83,324
BASIC EARNINGS PER SHARE	s	0.49	s	3.10	s	0.76
DILUTE D EARNINGS PER SHARE	\$	0.48	s	3.07	s	0.75
GAAP NET PROFIT	s	53,847	s	342,055	s	83,324
Stock based compensation		6,662		7,898		6,431
Amortization of acquired intangible assets		442		491		510
Restructuring income, net		_		-		(8,966)
Merger-contract termination fee, net	79	0-00 CO	1/2	(289,988)	123	
ADJUSTED NE T PROFIT	s	60,951	s	60,456	s	81,299
ADJUSTED DILUTE D EARNINGS PER SHARE						
Basic	s	0.55	s_	0.55	\$	0.74
Diluted	S	0.55	\$	0.54	S	0.73



## Financial Model (\$M)

			Built-out capacity	Incremental			
	2023	@85% utilization*		/11/2		\$M	% of Incremental Revenue
Revenue	1,423	1.9X	2,660	1,237			
Gross Profit	354	2.1X	740	386	31%		
Operating Profit	234 **	2.4X	560	326	26%		
Net Profit	229 **	2.2X	500	271	22%		

 $<sup>* \ \</sup>textit{Including New Mexico capacity corridor and Agrate capacity based on previously announced \textit{Cap-Ex investments} \\$ 



<sup>\*\*</sup> Excluding Intel merger contract termination fees received in Q3′2023, net of associated cost and taxes

